

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ying-Yao Lin	08/05/2006
Ying-Hsi Lin	08/05/2006
RECEIVING PARTY DATA	
Name:	Realtek Semiconductor Corp.
Street Address:	2 Innovation Rd. II, Science Park
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State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11462997
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NAME OF SUBMITTER:	WINSTON HSU
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REEL: 018066 FRAME: 0361

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Ying-Yao Lin Nationality: R.O.C.

Address: No. 17, Sec. 1, Guangming 10th St., Chubei City, Hsin-Chu Hsien, Taiwan, R.O.C.

Name: Ying-Hsi Lin Nationality: R.O.C.

Address: No. 23, Alley 1, Lane 30, Fu-Chiun St., Hsin-Chu City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Realtek Semiconductor Corp.

Address: 2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"APPARATUS AND METHOD FOR ENHANCING Q FACTOR OF INDUCTOR"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this AUG 05 2006 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Ying-Yao Lin

Ying-Hsi Lin

Signature of INVENTOR

Ying Yao Lin
Ying Hsi Lin

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